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PATENT APPLICATION  
Docket: 11948.36

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Tangpuz, et al.

Application No.: 10/678,010

Filing Date: October 2, 2003

Art Unit  
2818

Title: METHOD FOR MAINTAINING SOLDER  
THICKNESS IN FLIPCHIP ATTACH  
PACKAGING PROCESS

Examiner: Tu Tu Ho

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT  
UNDER 37 C.F.R. § 1.97

Mail Stop: DD  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Please find, pursuant to 37 C.F.R. § 1.98(a)(1), the enclosed Form PTO-1449 which contains a list of all documents that have come to the attention of one or more of the individuals designated in 37 C.F.R. § 1.56(c). While no representation is made that any of these references may be "prior art" within the meaning of that term under 35 U.S.C. §§ 102 or 103, the enclosed list of references is disclosed so as to fully comply with the duty of disclosure set forth in 37 C.F.R. § 1.56.

Moreover, while no representation is made that a specific search of office files or patent office records has been conducted or that no better art exists, the undersigned attorney of record

believes that the enclosed art is the closest to the claimed invention (taken in its entirety) of which the undersigned is presently aware, and no art which is closer to the claimed invention (taken in its entirety) has been knowingly withheld.

Please credit any over payment or charge any additional fees to Deposit Account No. 50-0843 of the undersigned.

DATED this 18 day of March 2005.

Respectfully submitted,



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KEH/jb



Form PTO-1449

Sheet 1 of 1

Applicant: Tanapuz, et al.

Serial No.: 10/678,010

Filing Date: October 2, 2003

For: METHOD FOR MAINTAINING SOLDER THICKNESS  
IN FLIPCHIP ATTACH PACKAGING PROCESS

Att'y Docket No. 11948.36

Group: 2828

INFORMATION DISCLOSURE CITATIONS MADE BY APPLICANT

Co-Pending Applications

Examiner <u>Initial*</u>	Application <u>Number</u>	Filing <u>Date</u>
_____ A1.	10/413,668	04/14/2003

U.S. Patent Documents

Examiner <u>Initial*</u>	Document <u>Number</u>	Issue <u>Date</u>	Name
_____ A2.	6,297,562	01/02/2001	Tilly
_____ A3.	6,307,755	10/23/2001	Williams, et al.
_____ A4.	6,391,758	04/21/2002	Lo, et al.
_____ A5.	6,720,642	04/13/2004	Joshi, et al.
_____ A6.	6,774,466	08/10/2004	Kijiwara, et al.

DOCS-#800206-v1-Supp\_IDS\_1449.DOC

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Examiner:

Date Considered:

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\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

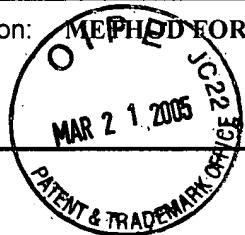
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**CERTIFICATE OF MAILING BY FIRST CLASS MAIL (37 CFR 1.8)**

Applicant(s): Tangpuz, et al.

Docket No.

11948.36

Application No.  
10/678,010Filing Date  
October 2, 2003Examiner  
Tu Tu HoCustomer No.  
27,966Group Art Unit  
2818Invention: **METHOD FOR MAINTAINING SOLDER THICKNESS IN FLIPCHIP ATTACH PACKAGING PROCESS**

I hereby certify that this **Supplemental Information Disclosure Statement Under 37 CFR 1.97 and 1449; check**  
(Identify type of correspondence)

is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope  
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**March 18, 2005**

*(Date)*

**JoAnn Bawden**

(*Typed or Printed Name of Person Mailing Correspondence*)

A handwritten signature of JoAnn Bawden.

(*Signature of Person Mailing Correspondence*)

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